SDAS224B - JUNE 1982 - REVISED NOVEMBER 1995

- Compare Two 8-Bit Words
- Choice of Totem-Pole or Open-Collector Outputs
- SN74ALS518 and 'ALS520 Have 20-kΩ
 Pullup Resistors on Q Inputs
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

TYPE	INPUT PULLUP RESISTOR	OUTPUT FUNCTION AND CONFIGURATION
SN74ALS518	Yes	P = Q open collector
'ALS520	Yes	$\overline{P} = Q$ totem pole
SN74ALS521 [‡]	No	$\overline{P} = Q$ totem pole

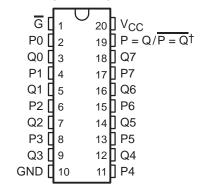
[‡]SN74ALS521 is identical to 'ALS688

description

These identity comparators perform comparisons on two 8-bit binary or BCD words. The SN74ALS518 provides P=Q outputs, while the 'ALS520' and SN74ALS521 provide $\overline{P}=\overline{Q}$ outputs. The SN74ALS518 has an open-collector output. The SN74ALS518 and 'ALS520' feature 20-k Ω pullup resistors on the Q inputs for analog or switch data.

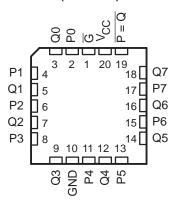
The SN54ALS520 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ALS518, SN74ALS520, and SN74ALS521 are characterized for operation from 0°C to 70°C.

SN54ALS520 . . . J PACKAGE SN74ALS518, SN74ALS520, SN74ALS521 . . . DW OR N PACKAGE (TOP VIEW)



 † P = Q for SN74ALS518 P = Q for 'ALS520 and SN74ALS521

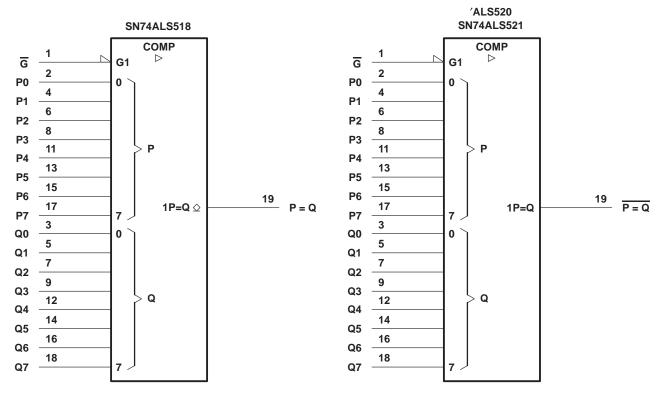
SN54ALS520 . . . FK PACKAGE (TOP VIEW)



FUNCTION TABLE

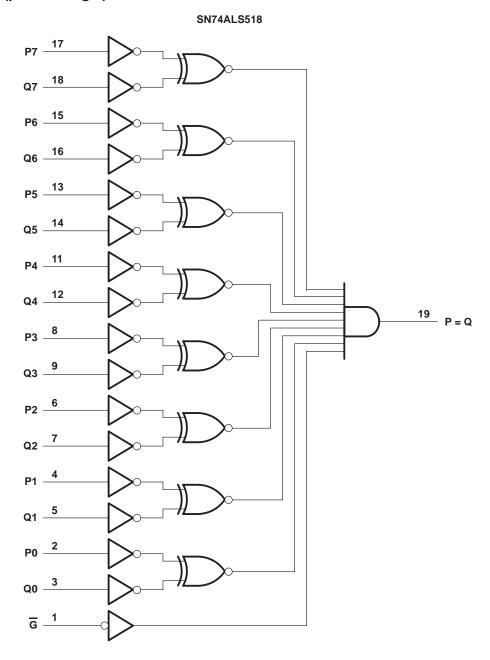
IN	PUTS	OUTPUTS				
DATA P, Q	ENABLE G	P = Q	P = Q			
P = Q	L	Н	L			
P > Q	L	L	Н			
P < Q	L	L	Н			
Х	Н	L	Н			

logic symbols†

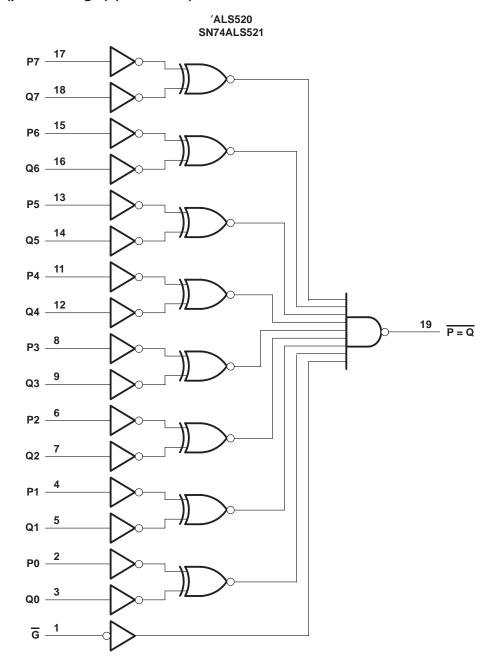


† These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagrams (positive logic)



logic diagrams (positive logic) (continued)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}	7 V
Input voltage, V _I : Q inputs	V _{CC} + 0.5 V or 5.5 V, whichever is less
All other inputs	7 V
Off-state output voltage	7 V
Operating free-air temperature range, T _A : SN74ALS518	
Storage temperature range	

recommended operating conditions

		SN	74ALS5	18	UNIT
		MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
Vон	High-level output voltage			5.5	V
IOL	Low-level output current			24	mA
TA	Operating free-air temperature	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DADAMETED	TEST CON	TEST CONDITIONS						
	PARAMETER	TEST CON	ONO	MIN	TYP [‡]	MAX	UNIT		
٧ıK		V _{CC} = 4.5 V,	$I_{I} = -18 \text{ mA}$			-1.5	V		
loh		V _{CC} = 5.5 V,	V _{OH} = 5.5 V			0.1	mA		
VOL		V00 - 45 V	I _{OL} = 12 mA		0.25	0.4	V		
		V _{CC} = 4.5 V	$I_{OL} = 24 \text{ mA}$		0.35	0.5	V		
1.	Q inputs	V00 - 5 5 V	V _I = 5.5 V			0.1	mA		
1 ₁	All other inputs	V _{CC} = 5.5 V	V _I = 7 V			0.1] "''^]		
la c	Q inputs	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	V _I = 2.7 V			-0.2	mA		
IН	All other inputs	V _{CC} = 5.5 V,	V = 2.7 V			20	μΑ		
	Q inputs	V FFV	V _I = 0.4 V			-0.6	mA		
IIL	All other inputs	V _{CC} = 5.5 V,	V = 0.4 V			-0.1	IIIA		
ICC		V _{CC} = 5.5 V,	See Note 1		11	17	mA		

‡ All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25 ^{\circ}\text{C}$.

NOTE 1: ICC is measured with G grounded, and P and Q at 4.5 V.



[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

SN54ALS520, SN74ALS518, SN74ALS520, SN74ALS521 8-BIT IDENTITY COMPARATORS

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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4.5 C _L = 50 pF R _L = 680 Ω T _A = MIN to SN74A	o MAX†	UNIT
t _{PLH}	D or O	В О	15	33	nc
^t PHL	P or Q	P = Q	3	15	ns
t _{PLH}	G	P = Q	15	33	ns
^t PHL	9	1 – Q	3	15	115

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V _{CC}	7 V
Input voltage, V _I : Q inputs of 'ALS520 V _{CC} + 0.5 V or 5.5 V, wh	ichever is less
All other inputs	7 V
Operating free-air temperature range, T _A : SN54ALS520	55°C to 125°C
SN74ALS520, SN74ALS521	. 0°C to 70°C
Storage temperature range – (65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN	54ALS5	20	_	74ALS5 74ALS5	-	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.7			0.8	V
ІОН	High-level output current			-1			-2.6	mA
loL	Low-level output current			12			24	mA
TA	Operating free-air temperature	-55		125	0		70	°C

SDAS224B – JUNE 1982 – REVISED NOVEMBER 1995

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST COI	NDITIONS	SN	54ALS5	20	SN74ALS520 SN74ALS521			UNIT
							MIN	TYP [†]	MAX	
٧ıK		V _{CC} = 4.5 V,	$I_{I} = -18 \text{ mA}$			-1.5			-1.5	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2	2		V _{CC} -2)		
Vон		V45V	$I_{OH} = -1 \text{ mA}$	2.4	3.3					V
		V _{CC} = 4.5 V	$I_{OH} = -2.6 \text{ mA}$				2.4	3.2		
VOL		V00 - 45 V	I _{OL} = 12 mA		0.25	0.4		0.25	0.4	V
		VCC = 4.5 V	I _{OL} = 24 mA					0.35	0.5	v
ı.	'ALS520 Q inputs	V00 - 5 5 V	V _I = 5.5 V			0.1			0.1	mA
11	All other inputs	VCC = 5.5 V	V _I = 7 V			0.1			0.1	mA
	'ALS520 Q inputs	V 55V	V- 2.7.V			-0.2			-0.2	mA
lіН	All other inputs	$V_{CC} = 5.5 \text{ V},$	$V_1 = 2.7 \text{ V}$			20			20	μΑ
	'ALS520 Q inputs	V 55V	V: 0.4.V			-0.6			-0.6	A
IIL.	All other inputs	V _{CC} = 5.5 V,	$V_{ } = 0.4 \text{ V}$			-0.1			-0.1	mA
10 [‡]		V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA
	'ALS520	V 55V	Coo Note 4		12	19		12	19	A
ICC	SN74ALS521	V _{CC} = 5.5 V,	See Note 1		12	19		12	19	mA

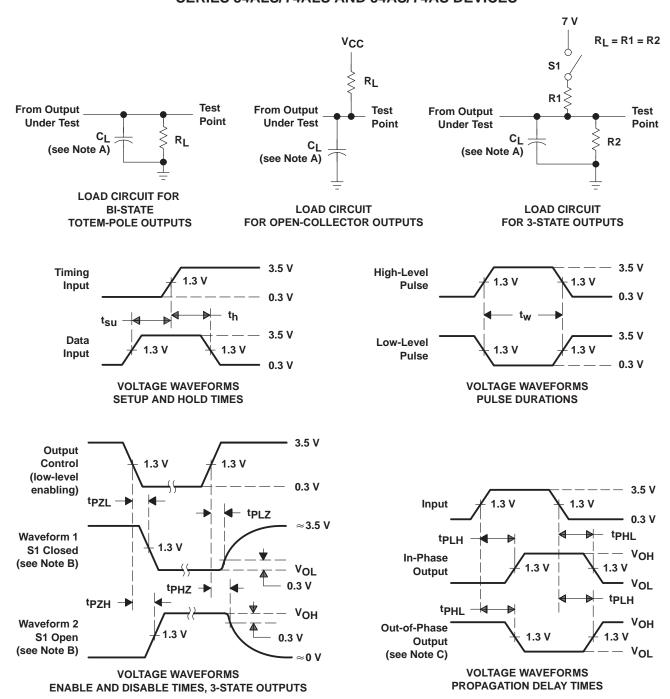
switching characteristics (see Figure 1)

PARAMETER	FROM	то	V _C C _L R _L T _A	UNIT			
	(INPUT)	(OUTPUT)	SN54A	LS520	SN74A SN74A		
			MIN	MAX	MIN	MAX	
^t PLH	D an O	$\overline{P} = Q$	3	19	3	12	ns
^t PHL	P or Q	P = Q	3	25	5	20	115
t _{PLH}	G	P = Q	2	18	2	12	ns
tPHL .	J	1 – Q	5	23	5	22	113

[§] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. ‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, los. NOTE 1: I_{CC} is measured with \overline{G} grounded, and P and Q at 4.5 V.

PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, $t_f = t_f = 2$ ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms







25-Sep-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type	_	Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)		(3)		(4/5)	
5962-88691012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 88691012A SNJ54ALS 520FK	Samples
5962-8869101RA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8869101RA SNJ54ALS520J	Samples
SN54ALS520J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54ALS520J	Samples
SN74ALS518DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS518	Samples
SN74ALS518DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS518	Samples
SN74ALS518DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS518	Samples
SN74ALS518N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS518N	Samples
SN74ALS518NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS518N	Samples
SN74ALS518NS	PREVIEW	y so	NS	20		Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS518	
SN74ALS520DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS520	Samples
SN74ALS520DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS520	Samples
SN74ALS520DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS520	Samples
SN74ALS520N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS520N	Samples
SN74ALS520NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS520N	Samples
SN74ALS520NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS520	Samples
SN74ALS520NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS520	Samples





25-Sep-2013

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ALS520NSRG4	ACTIVE	so	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS520	Samples
SN74ALS521DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS521	Samples
SN74ALS521DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS521	Samples
SN74ALS521DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS521	Samples
SN74ALS521DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS521	Samples
SN74ALS521DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS521	Sample
SN74ALS521DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS521	Sample
SN74ALS521N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS521N	Sample
SN74ALS521NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS521N	Sample
SN74ALS521NSR	ACTIVE	so	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS521	Sample
SN74ALS521NSRE4	ACTIVE	so	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS521	Sample
SN74ALS521NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS521	Sample
SNJ54ALS520FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 88691012A SNJ54ALS 520FK	Sample
SNJ54ALS520J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8869101RA SNJ54ALS520J	Sample

⁽¹⁾ The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

PACKAGE OPTION ADDENDUM



25-Sep-2013

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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OTHER QUALIFIED VERSIONS OF SN54ALS520, SN74ALS520:

Catalog: SN74ALS520

Military: SN54ALS520

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

14-Jul-2012 www.ti.com

TAPE AND REEL INFORMATION

REEL DIMENSIONS





TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS520NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1
SN74ALS521DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74ALS521NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1

PACKAGE MATERIALS INFORMATION

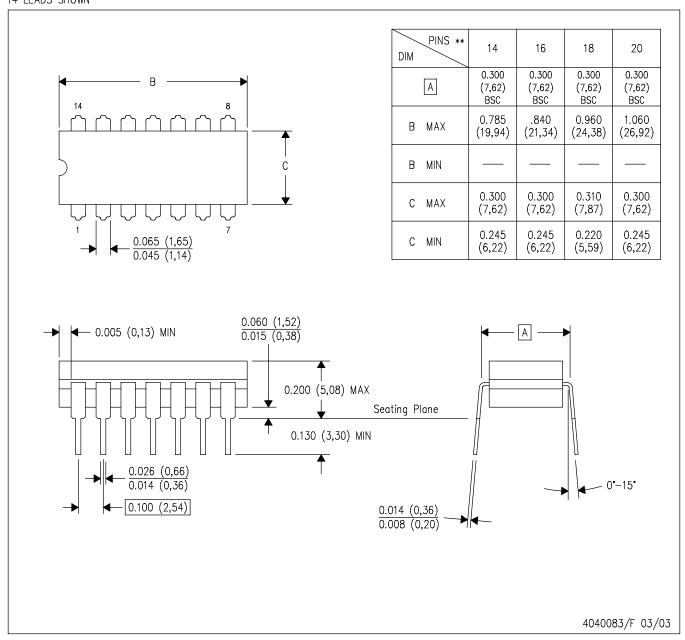
www.ti.com 14-Jul-2012



*All dimensions are nominal

7 th difficition and from that								
Device	Package Type	Package Drawing	Pins SPQ		Length (mm)	Width (mm)	Height (mm)	
SN74ALS520NSR	SO	NS	20	2000	367.0	367.0	45.0	
SN74ALS521DWR	SOIC	DW	20	2000	367.0	367.0	45.0	
SN74ALS521NSR	SO	NS	20	2000	367.0	367.0	45.0	

14 LEADS SHOWN

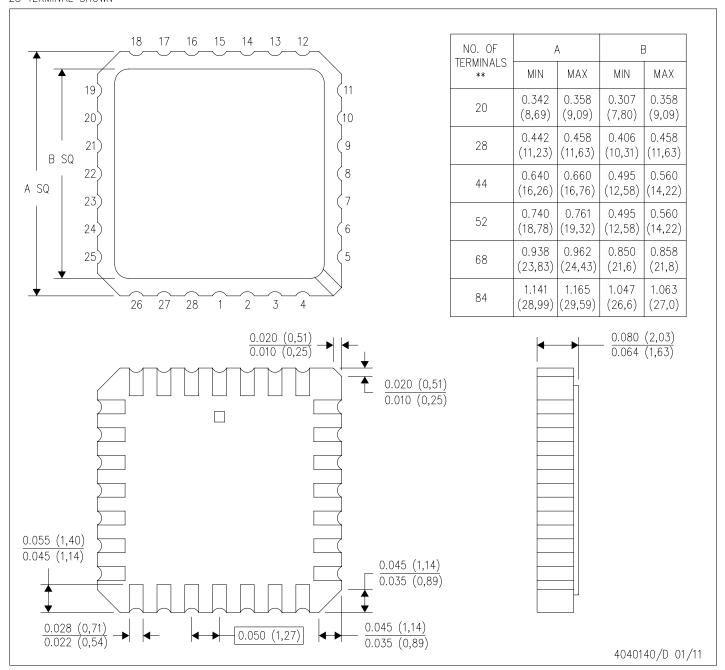


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



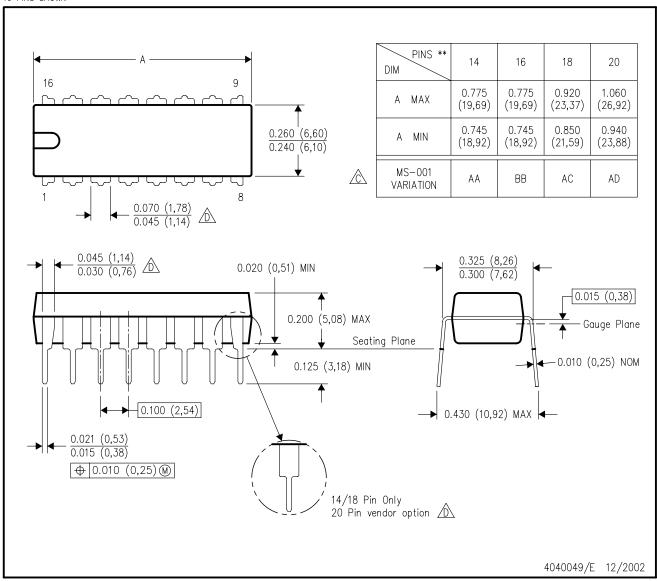
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



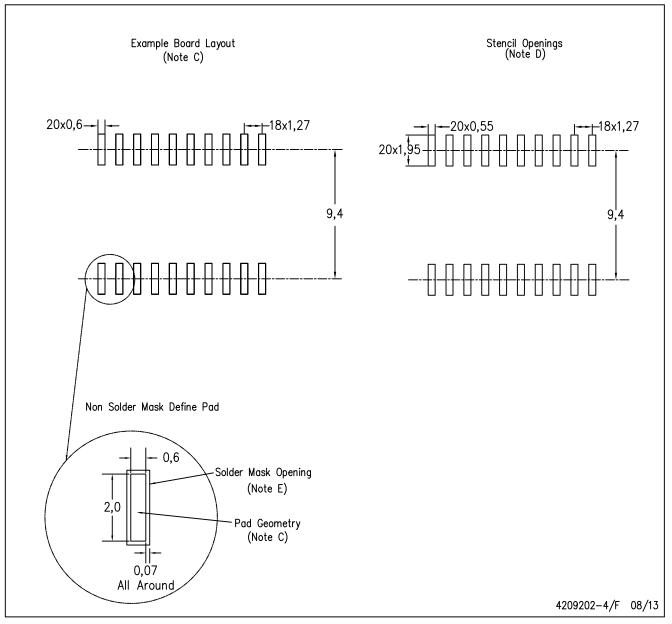
NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

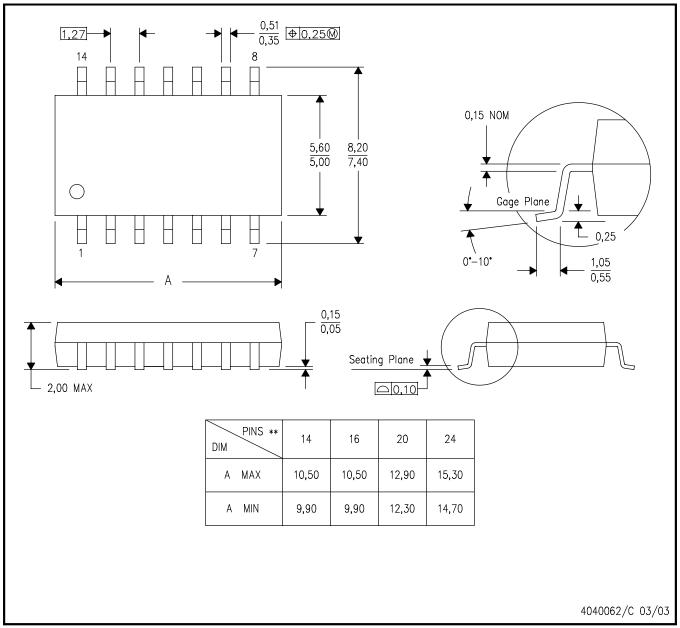


MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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